Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **CATHODE**
2. **REF**
3. **ANODE**

**.041”**

**.051”**

**TL431E**

**MASK**

**REF**

**2**

**3**

**1**

**Top Material: Al**

**Backside Material: SiNi**

**Bond Pad Size: .004” X .004”**

**Backside Potential: ANODE or FLOATING**

**Mask Ref: TL431E**

**APPROVED BY: DK DIE SIZE .041” X .051” DATE: 4/27/23**

**MFG: TEXAS INSTRUMENTS THICKNESS .015” P/N: TL431**

**DG 10.1.2**

#### Rev B, 7/19/02